

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

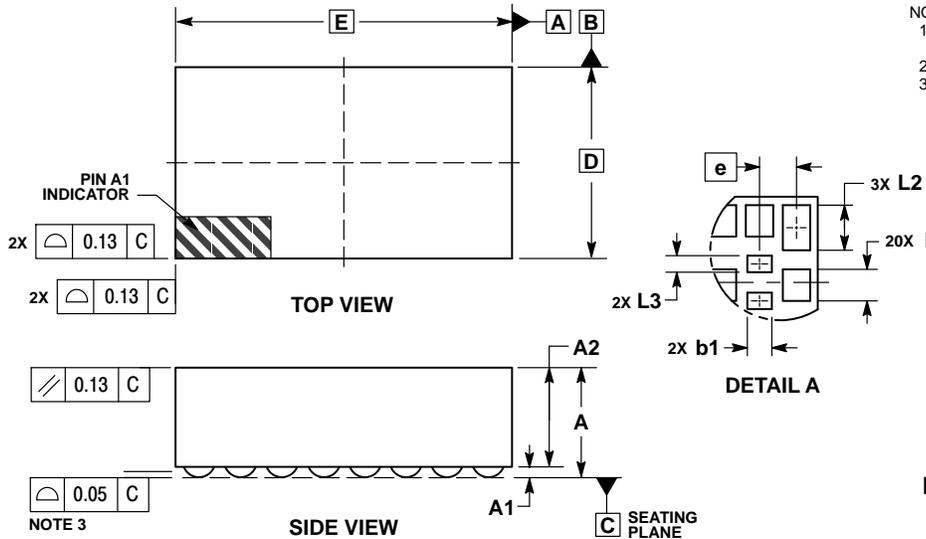
ON Semiconductor®



SCALE 2:1

SIP25, 5.59x3.18
CASE 127DN
ISSUE O

DATE 13 NOV 2014



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE PADS.

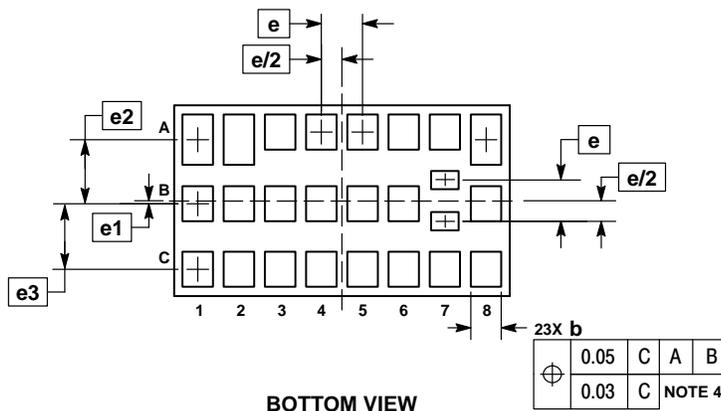
DIM	MILLIMETERS	
	MIN	MAX
A	---	1.83
A1	0.08	0.18
A2	---	1.65
b	0.478	0.538
b1	0.427	0.487
D	3.18 BSC	
E	5.59 BSC	
e	0.686 BSC	
e1	0.051 BSC	
e2	1.067 BSC	
e3	1.092 BSC	
L	0.554	0.614
L2	0.808	0.868
L3	0.275	0.335

GENERIC MARKING DIAGRAM*

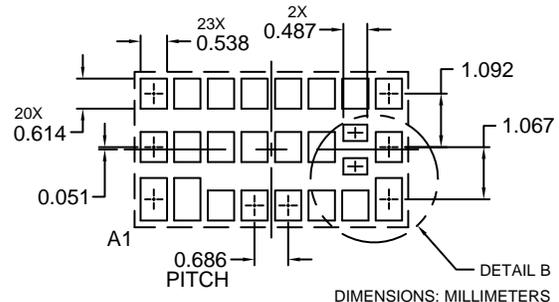


- XX = Specific Device Code
= Work Order Number

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "•", may or may not be present.



RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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